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INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 7 : H05K 1/09 — A1

(11) International Publication Number: **WO 00/33625**

(43) International Publication Date: 8 June 2000 (08.06.00)

(21) International Application Number: PCT/GB99/04064

(22) International Filing Date: 3 December 1999 (03.12.99)

(30) Priority Data:

9826446.8	3 December 1998 (03.12.98)	GB
9826447.6	3 December 1998 (03.12.98)	GB

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(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published

With international search report.

Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.

(54) Title: PROCESS FOR DEPOSITING CONDUCTING LAYER ON SUBSTRATE

(57) Abstract

A process for forming a conductive layer on a substrate, comprising the steps of depositing ink on the substrate by means of lithographic printing to form a seeding layer, and depositing a first electrically conducting layer on the seeding layer by electroless deposition.